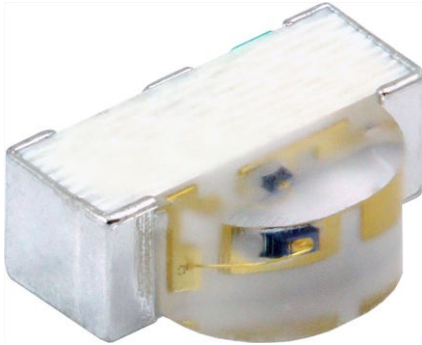


High Speed Infrared Emitting Diode, 850 nm, GaAlAs, DH



DESCRIPTION

VSMG10850 is an infrared, 850 nm side looking emitting diode in GaAlAs double hetero (DH) technology with high radiant power and high speed, molded in clear, untinted plastic package for surface mounting (SMD).

FEATURES

- Package type: Surface mount
- Package form: Side view
- Dimensions (L x W x H in mm): 3 x 2 x 1
- Peak wavelength: $\lambda_p = 850$ nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity: $\phi = \pm 75^\circ$
- Low forward voltage
- Package matches with detector VEMD10940F
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- IR touch panel
- High power emitter for low space applications
- High performance transmissive or reflective sensors

PRODUCT SUMMARY

| COMPONENT | I_e (mW/sr), 20 mA | ϕ (deg) | λ_p (nm) | t_r (ns) |
|-----------|----------------------|--------------|------------------|------------|
| VSMG10850 | 1 | ± 75 | 850 | 15 |

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
|---------------|---------------|------------------------------|--------------|
| VSMG10850 | Tape and reel | MOQ: 3000 pcs, 3000 pcs/reel | side view |

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
|-------------------------------------|---|------------|---------------|------------------|
| Reverse voltage | | V_R | 5 | V |
| Forward current | | I_F | 65 | mA |
| Peak forward current | $t_p/T = 0.5$, $t_p = 100 \mu\text{s}$ | I_{FM} | 130 | mA |
| Surge forward current | $t_p = 100 \mu\text{s}$ | I_{FSM} | 500 | mA |
| Power dissipation | | P_V | 110 | mW |
| Junction temperature | | T_j | 100 | $^\circ\text{C}$ |
| Operating temperature range | | T_{amb} | - 40 to + 85 | $^\circ\text{C}$ |
| Storage temperature range | | T_{stg} | - 40 to + 100 | $^\circ\text{C}$ |
| Soldering temperature | according to fig. 9, J-STD-020 | T_{sd} | 260 | $^\circ\text{C}$ |
| Thermal resistance junction/ambient | J-STD-051, leads 7 mm, soldered on PCB | R_{thJA} | 450 | K/W |

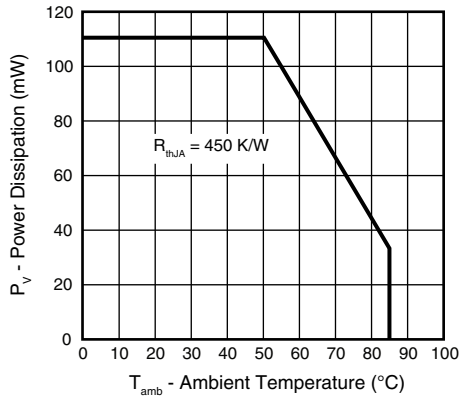


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

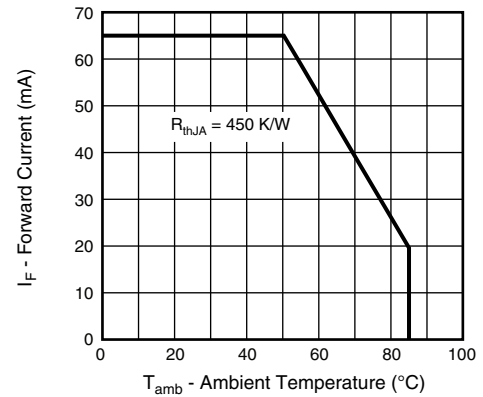


Fig. 2 - Forward Current Limit vs. Ambient Temperature

| BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified) | | | | | | |
|---|--|-----------------------------|------|--------|------|-------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Forward voltage | I _F = 20 mA, t _p = 20 ms | V _F | 1.1 | 1.4 | 1.65 | V |
| | I _F = 65 mA, t _p = 20 ms | V _F | | 1.45 | | V |
| | I _F = 500 mA, t _p = 100 μs | V _F | | 1.9 | | V |
| Temperature coefficient of V _F | I _F = 1 mA | TK _{V_F} | | - 1.8 | | mV/K |
| Reverse current | V _R = 5 V | I _R | | | 10 | μA |
| Junction capacitance | V _R = 0 V, f = 1 MHz, E = 0 mW/cm ² | C _J | | 45 | | pF |
| Radiant intensity | I _F = 20 mA, t _p = 20 ms | I _e | 0.6 | 1 | 1.8 | mW/sr |
| | I _F = 65 mA, t _p = 20 ms | I _e | | 3.25 | | mW/sr |
| | I _F = 500 mA, t _p = 100 μs | I _e | | 24 | | mW/sr |
| Radiant power | I _F = 100 mA, t _p = 20 ms | φ _e | | 40 | | mW |
| Temperature coefficient of radiant power | I _F = 1 mA | TK _{φ_e} | | - 1.1 | | %/K |
| Angle of half intensity - horizontal | | φ _h | | ± 77.5 | | deg |
| Angle of half intensity - vertical | | φ _v | | ± 72.5 | | deg |
| Peak wavelength | I _F = 30 mA | λ _p | | 850 | | nm |
| Spectral bandwidth | I _F = 30 mA | Δλ | | 40 | | nm |
| Temperature coefficient of λ _p | I _F = 30 mA | TK _{λ_p} | | 0.25 | | nm |
| Rise time | I _F = 100 mA, 20 % to 80 % | t _r | | 20 | | ns |
| Fall time | I _F = 100 mA, 20 % to 80 % | t _f | | 20 | | ns |

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

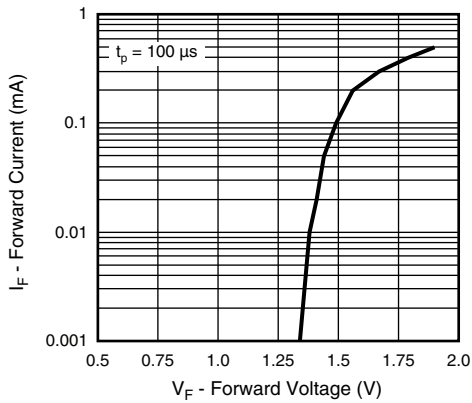


Fig. 3 - Forward Current vs. Forward Voltage

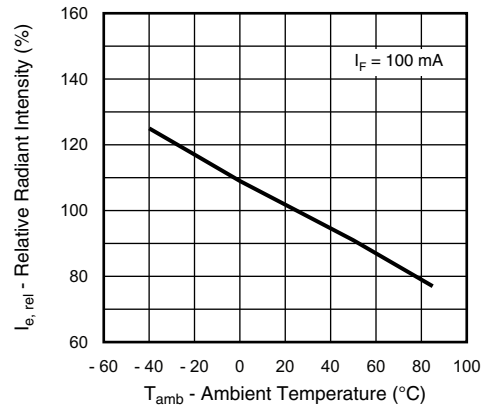


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

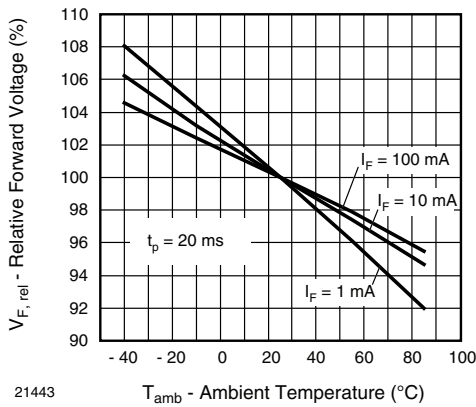


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

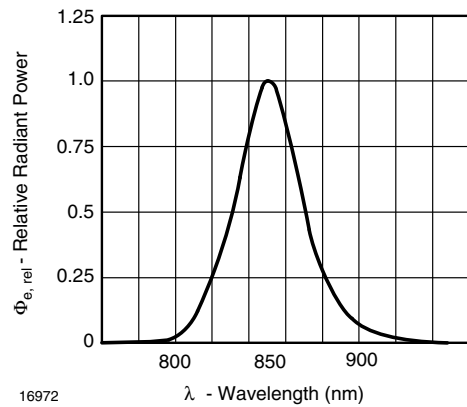


Fig. 7 - Relative Radiant Power vs. Wavelength

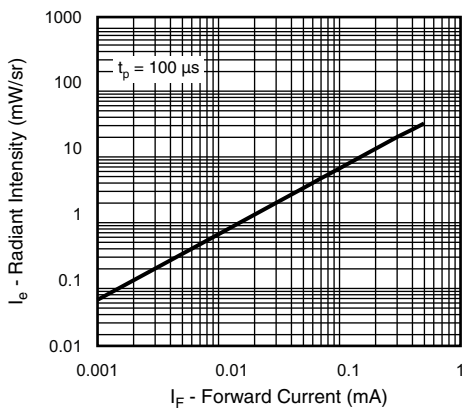


Fig. 5 - Radiant Intensity vs. Forward Current

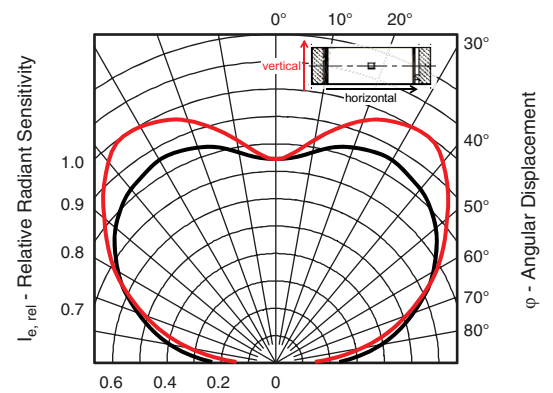


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

REFLOW SOLDER PROFILE

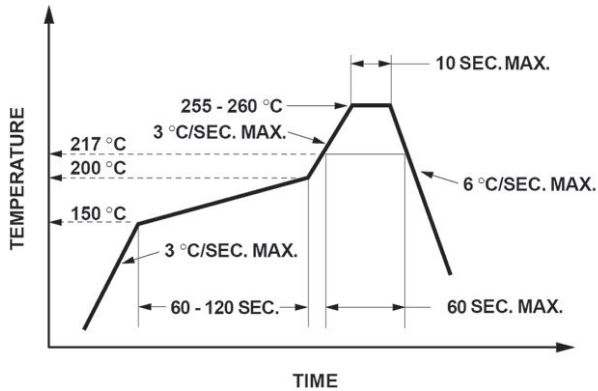


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

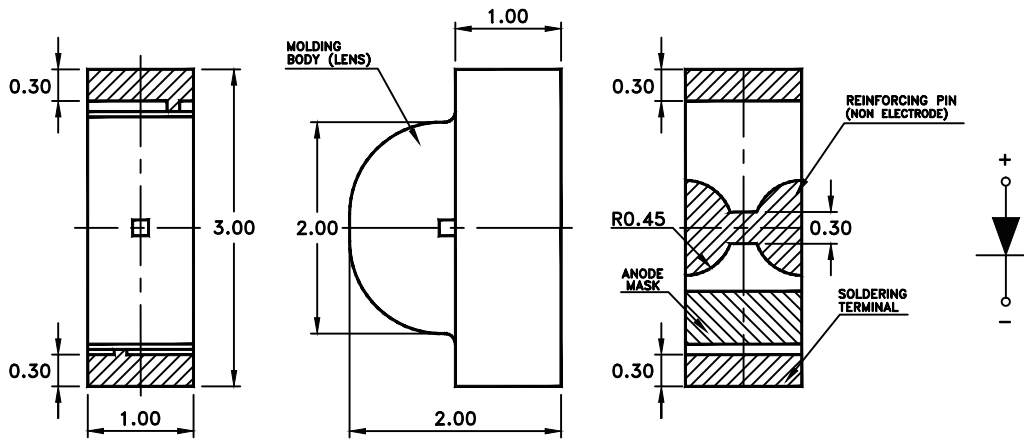
Floor life: 168 h

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, $\text{RH} < 60\text{ } \%$

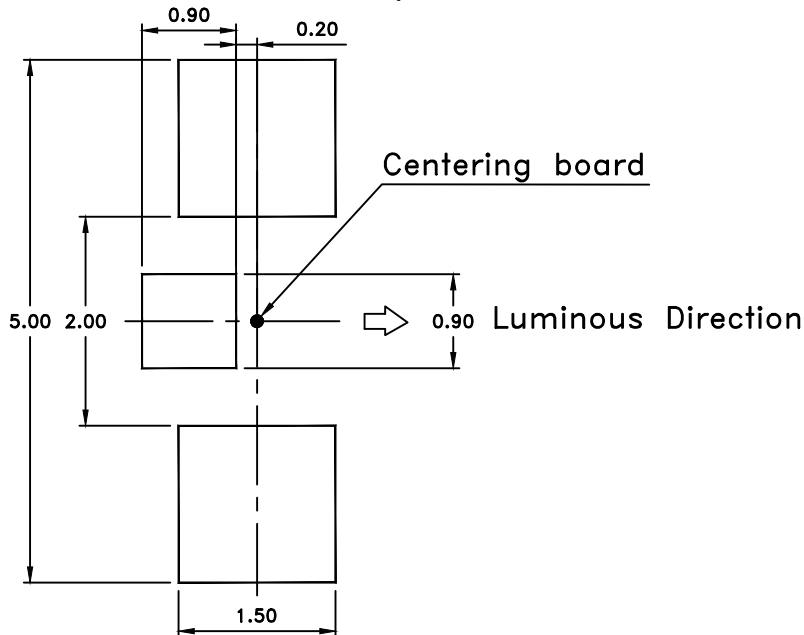
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C}$ (+ 5 $^{\circ}\text{C}$), $\text{RH} < 5\text{ } \%$.

PACKAGE DIMENSIONS in millimeters

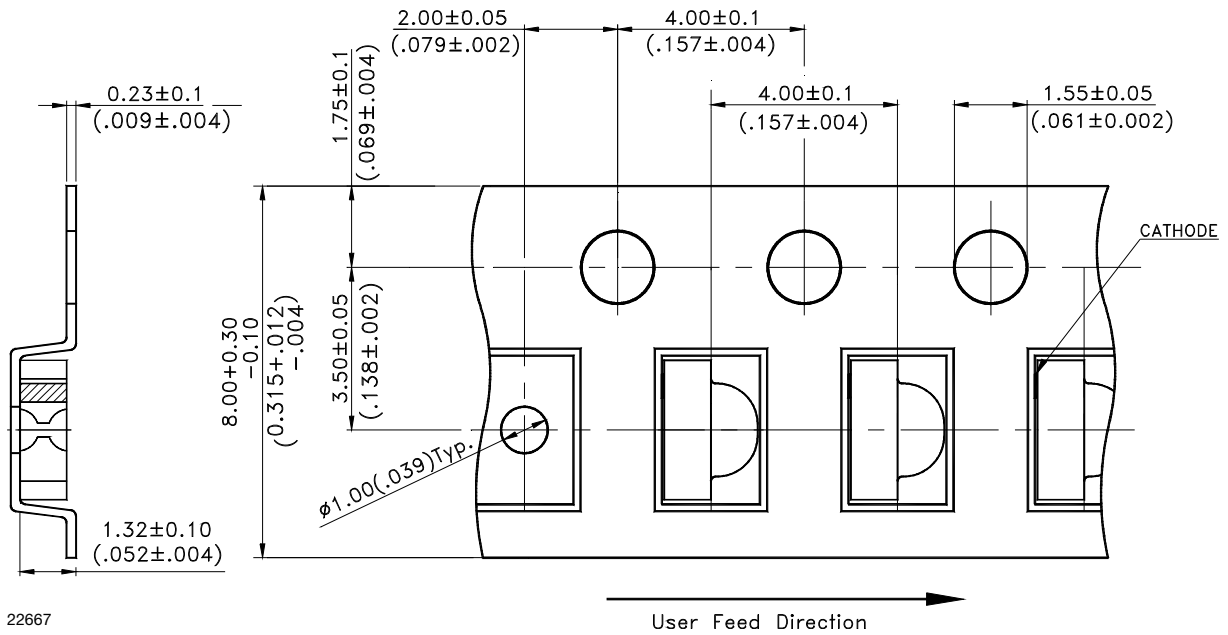


Recommended Solder Pad Footprint

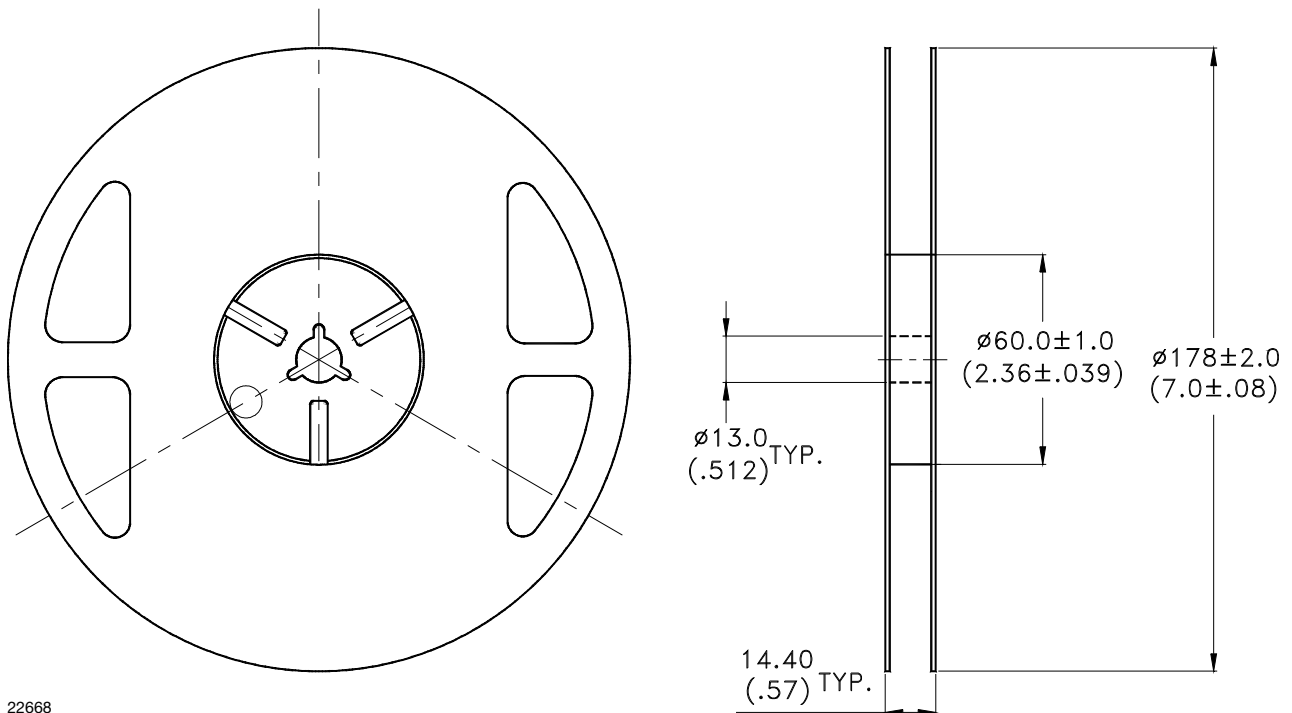


22666

BLISTER TAPE DIMENSIONS in millimeters



REEL DIMENSIONS in millimeters





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